fully automatic

automation level

manual

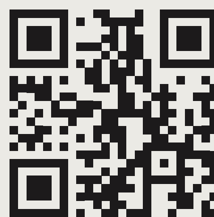
58 SERIES

56 SERIES

53 SERIES

> 1 Bonds/day 100.000

TECHNOLOGY	SERIES 53	SERIES 56	SERIES 58
GOLD-BALL	5310, 53xx BDA	5610	5810
THIN WIRE WEDGE-WEDGE	5330	5630	5830
THIN WIRE DEEP ACCESS	53xx BDA	5632	5832
HEAVY WIRE	5350	5650	5850
HEAVY RIBBON	5350 HR	5650 HR	5850 HR



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BONDING THE STARS

D. Seidl 2015 vers. 1

SERIES 53
SMALL. MANUAL. EASY.

ENGLISH

53 SERIES

BONDING THE STARS

SERIES 53
The Development Machine

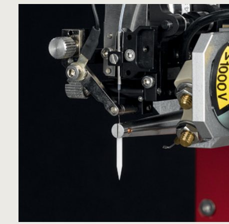
You need: 1 up to 1000 BONDS PER DAY
- >> In-house production to protect your technology and to provide short Time-to-Market
- >> Wirebonder for small production volumes; high quality requirements
- >> High mix / low volume; frequent product changes; small volumes
- >> Reproduceable Bonding results
- >> Repair works or R&D

THE SOLUTION: SERIES 53
- >> Complete, manual table top bonder
- >> Unbeatable price-to-performance ratio
- >> Extremely adaptable bond settings, loop shapes, force and power profiles etc.
- >> Dual wire clamp system for reproduceable loop and tails
- >> Easy handling

53 SERIES

BONDHEADS

F//S BONDTEC

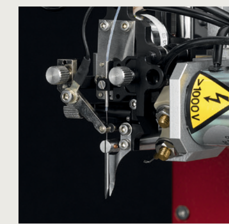


5310 – Gold-Ball

- >> Gold-Ball-Bonding for wires from 17,5 to 50 µm using Standard-Capillaries 16 mm to 19 mm
- >> Dual frequency-US-generator for 60/100 kHz further Bondfrequencies available on request
- >> Bumping, Safety-Bump, Stitch-on-Ball
- >> Programmable Z-Axis 60mm

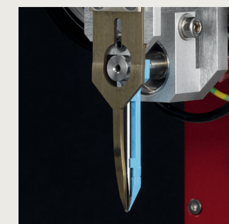
5330 – Thin wire Wedge-Wedge

- >> Wedge-Wedge-Bonding with 1" Tools for Aluminum- and Goldwires from 17,5 to 75 µm and ribbon up to 250x25µ
- >> 45° wireguide, retrofitable to 30° and 60° – according to component geometry
- >> Dual frequency-US-generator for 60/100 kHz further Bondfrequencies available on request
- >> Programmable Z-Axis 60mm and Y-Axis 25mm



53xx BDA – Ball-DeepAccess

- >> Wedge-Wedge-Bonding with 1" or ¾" Tools
- >> 90° wireguide for Aluminum- and Goldwires from 17,5 to 75 µm
- >> Gold-Ball-Bonding for wires from 17,5 to 50 µm with capillaries 16 -19 mm
- >> Perfect for difficult and constricted bonding geometries
- >> Also useable for ribbon of aluminum und gold
- >> Programmable Z-Axis 60mm and Y-Axis 25mm
- >> optional: retrofitable to 5380 DIE-Bonder

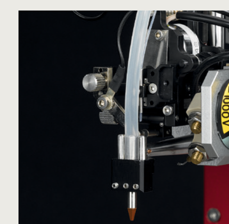


5350 – Heavy-Wire

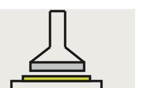
- >> Wedge-Wedge-Bonding for aluminum heavy wire from 100 to 500 µm diameter // copper from 100 to 300 µm
- >> Wedge-Tool length from 50 to 70 mm also for extreme bonding requirements
- >> Stitch- or chain bonds of any length
- >> Clip-on-wire guide for quick exchange
- >> Optional: retrofitable to 5350 HR heavy ribbon bondhead
- >> Programmable Z-Axis 60mm and Y-Axis 25mm

5350 HR– Heavy Ribbon

- >> Wedge-wedge bonding for heavy aluminum or copper ribbons up to 2mm width
- >> Increased programmable bond force up to 6,000 cN, also with force and power ramps
- >> Active ribbon guide to improve loop shaping
- >> Programmable Z-Axis 60mm and Y-Axis 25mm



5380 – optional: DIE-Bonder



- >> Different DIE-sizes process oriented useable
- >> manual DIE-bonding with Touchdown-Detection and programmable pickup- and bond force
- >> 2x2" working area for any Waffle-, Gel-Packs or Trays
- >> Bond- and pickup force from 5 up to 500 cN programmable